

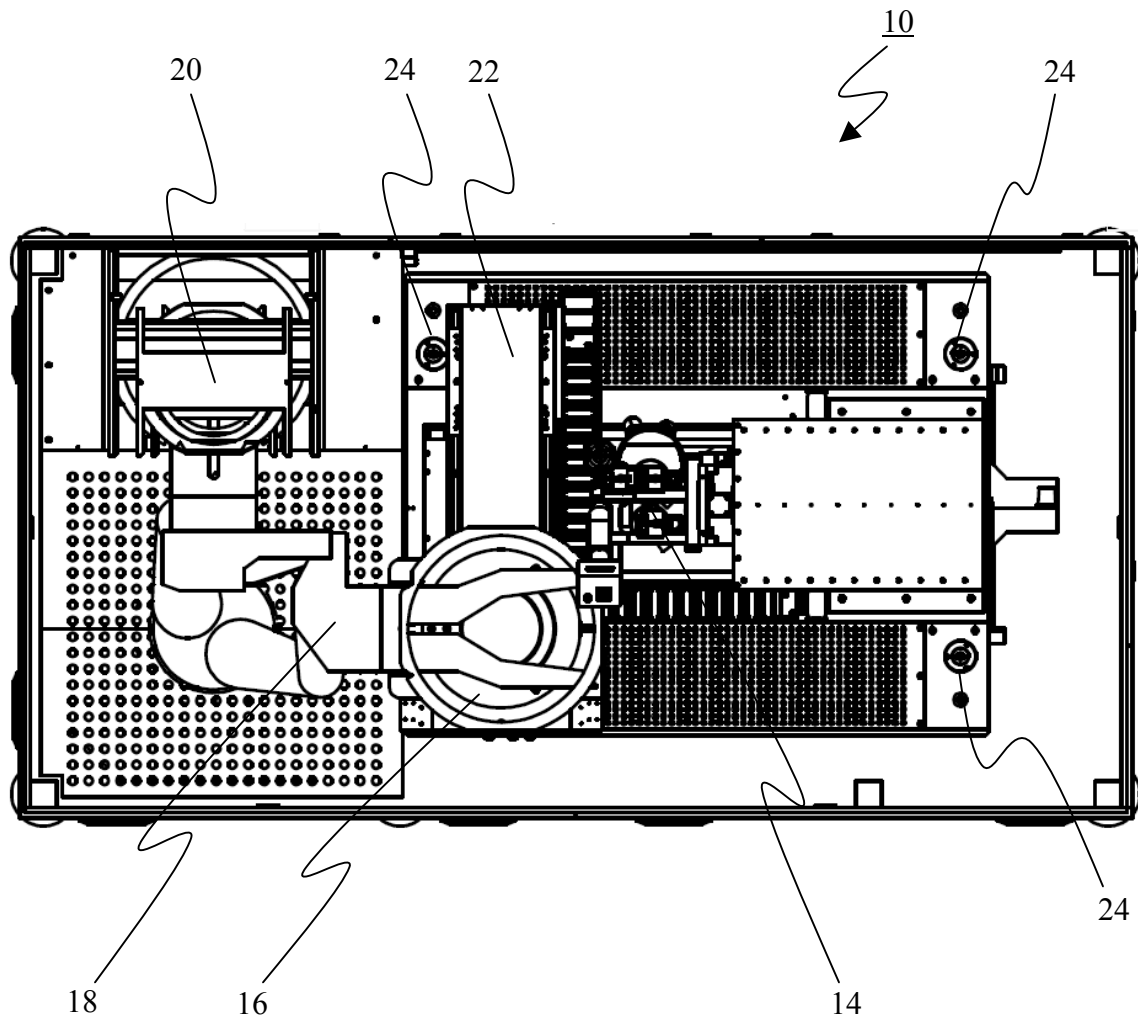
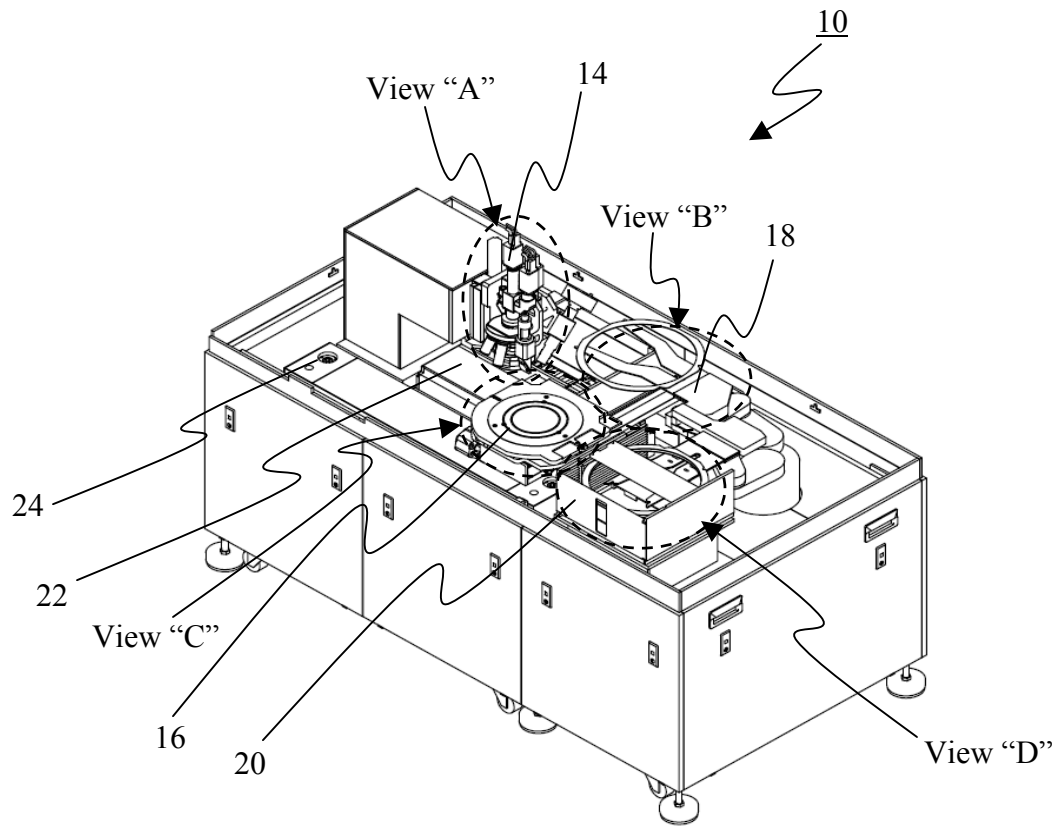


FIG. 1

**FIG. 2**

View "A"

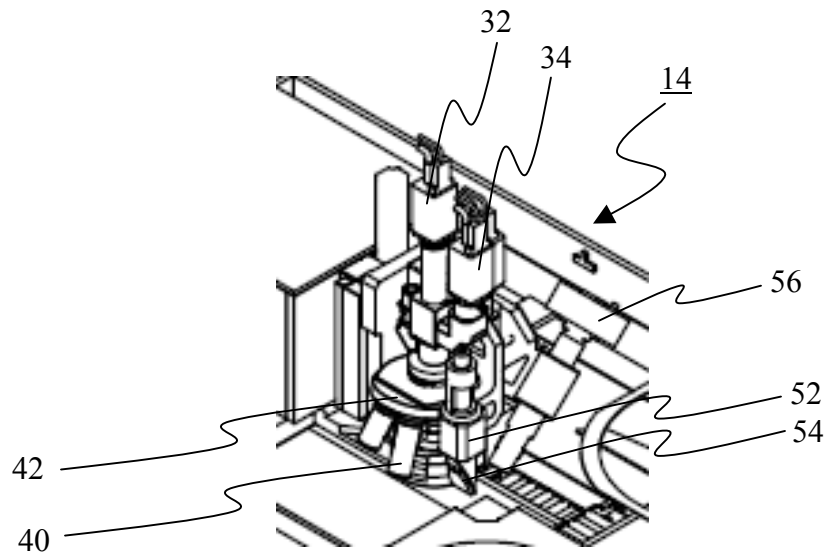


FIG. 3

View "B"

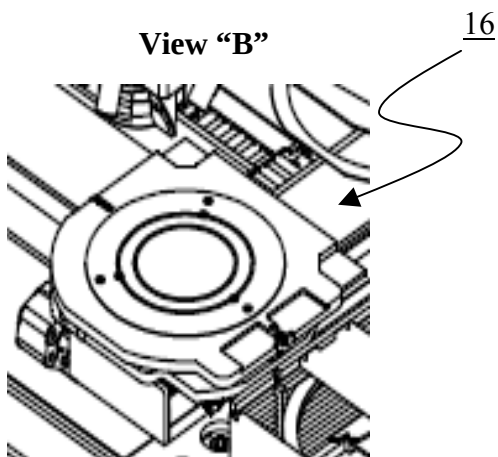


FIG. 4

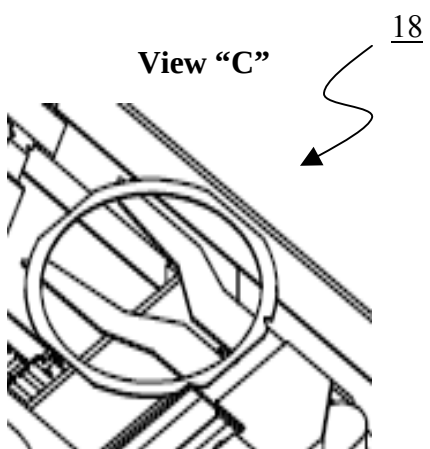


FIG. 5

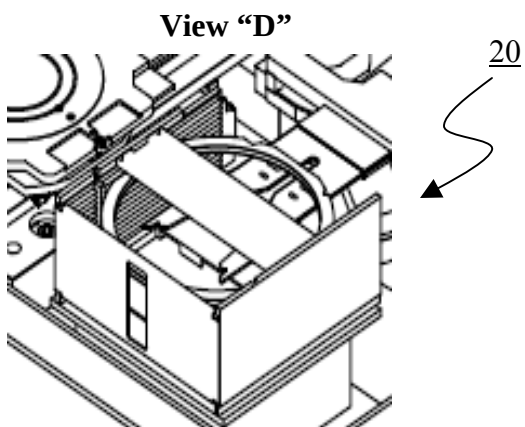


FIG. 6

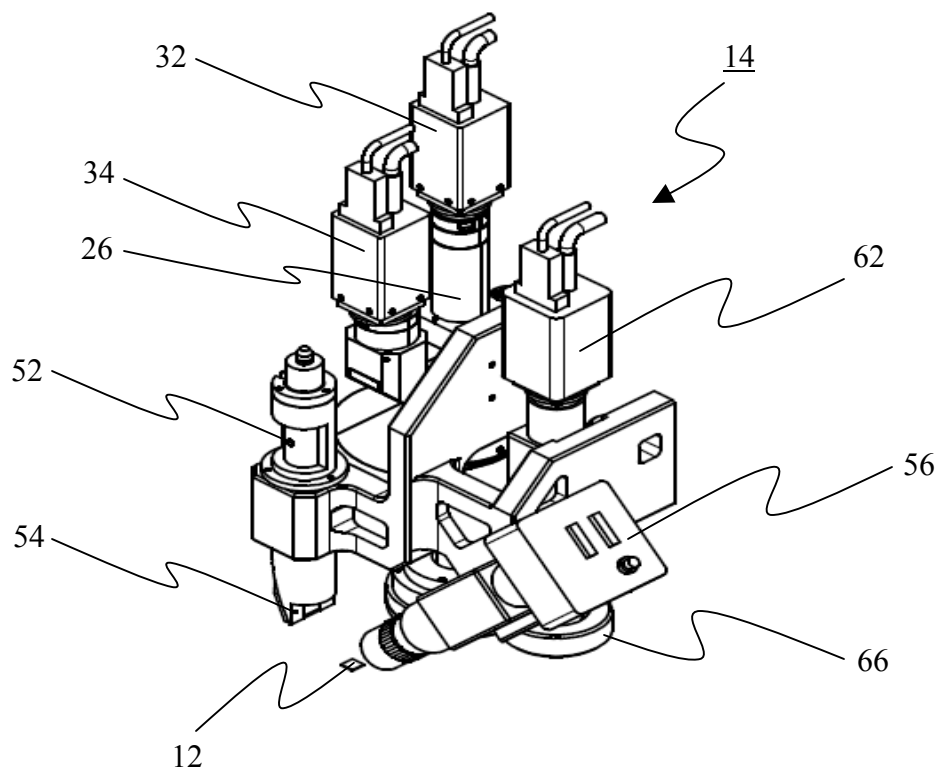


FIG. 7

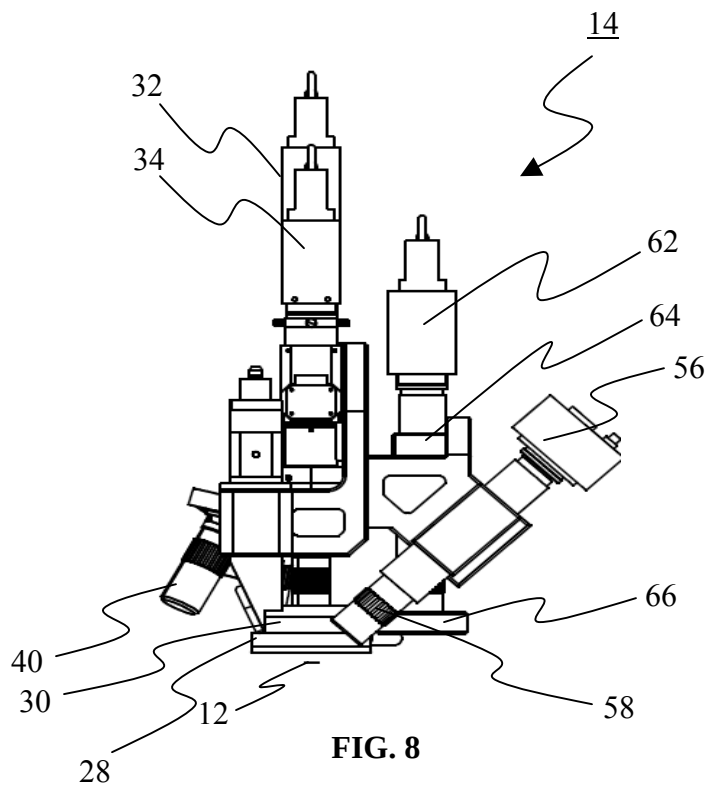


FIG. 8

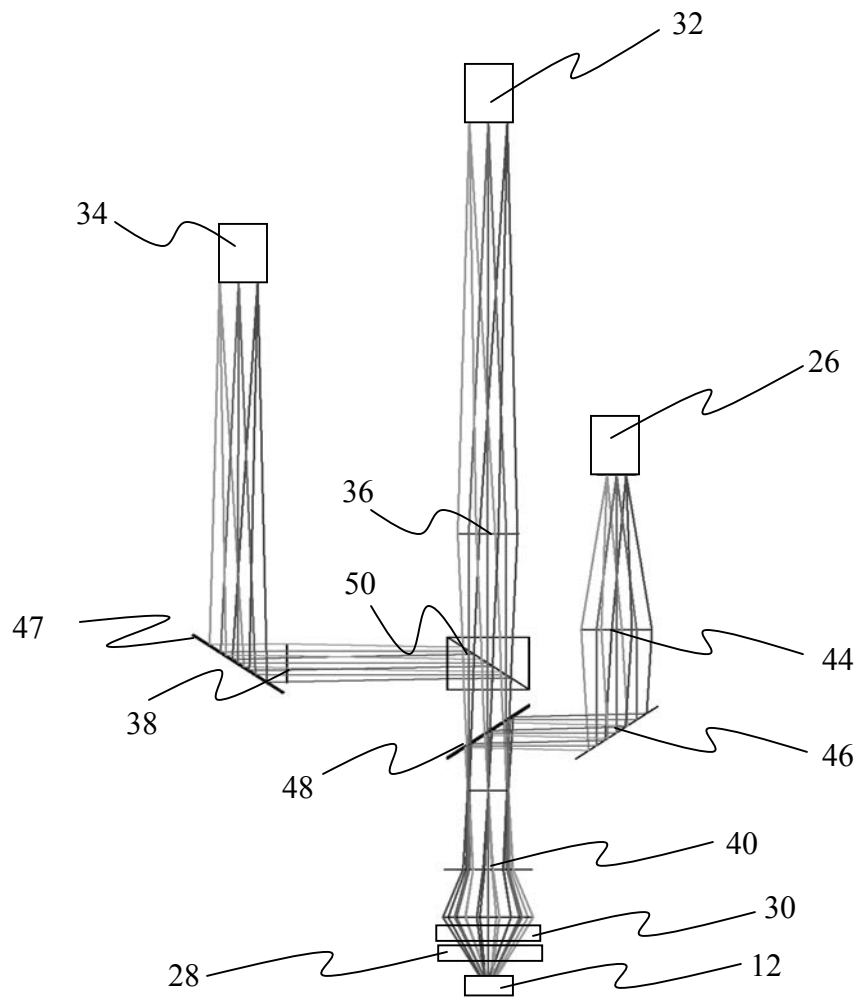


FIG. 9

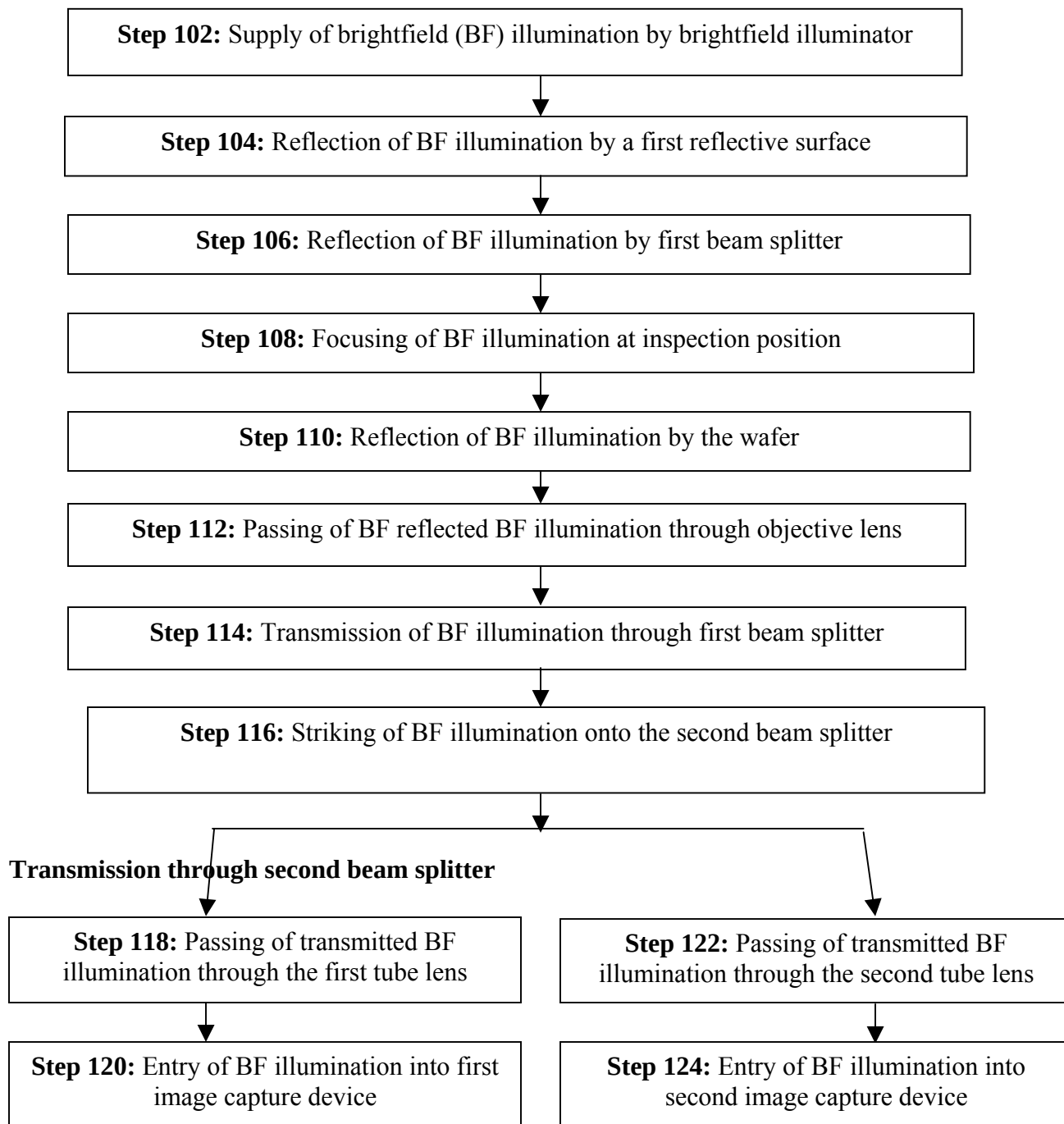


FIG. 10

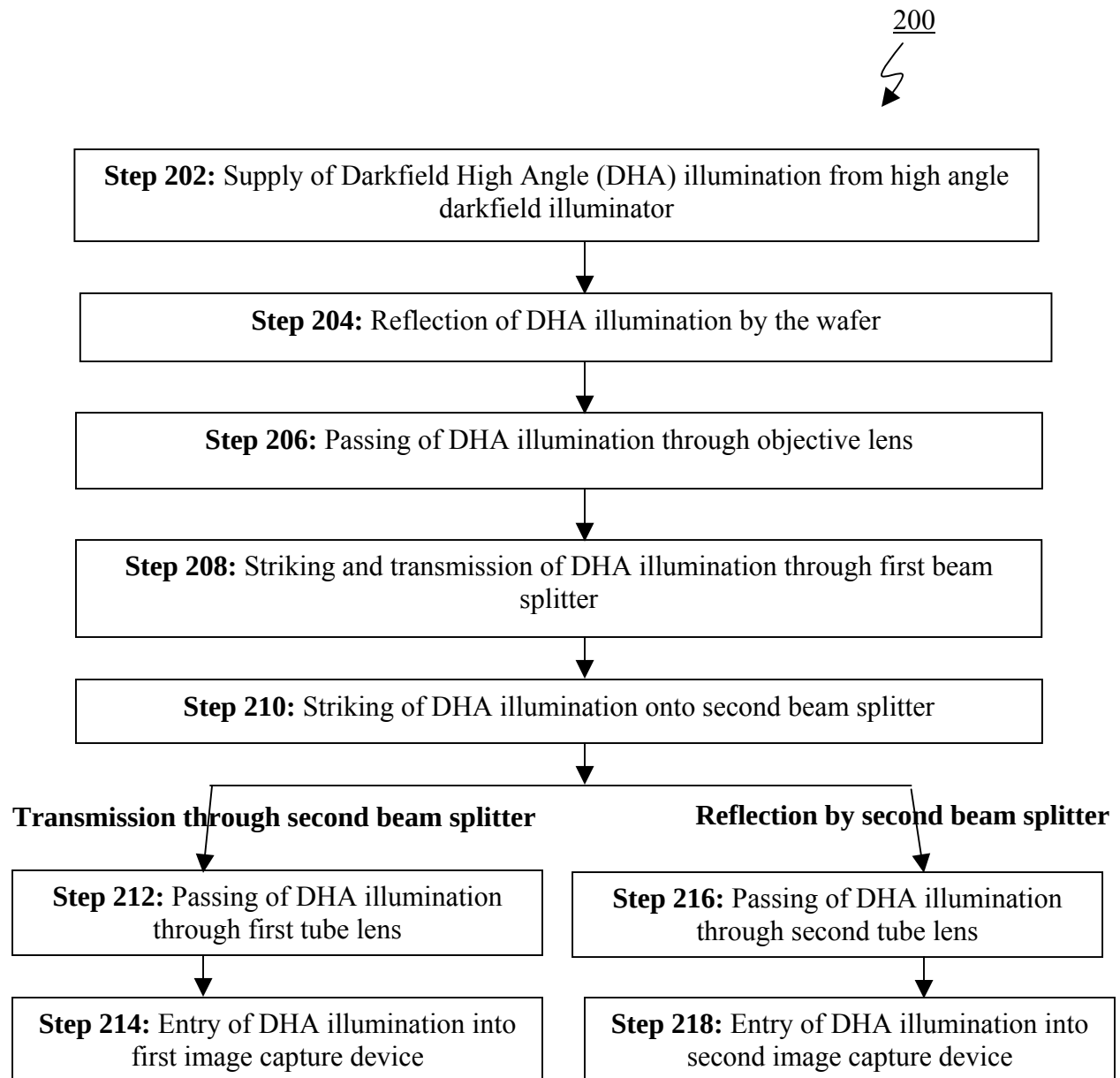


FIG. 11

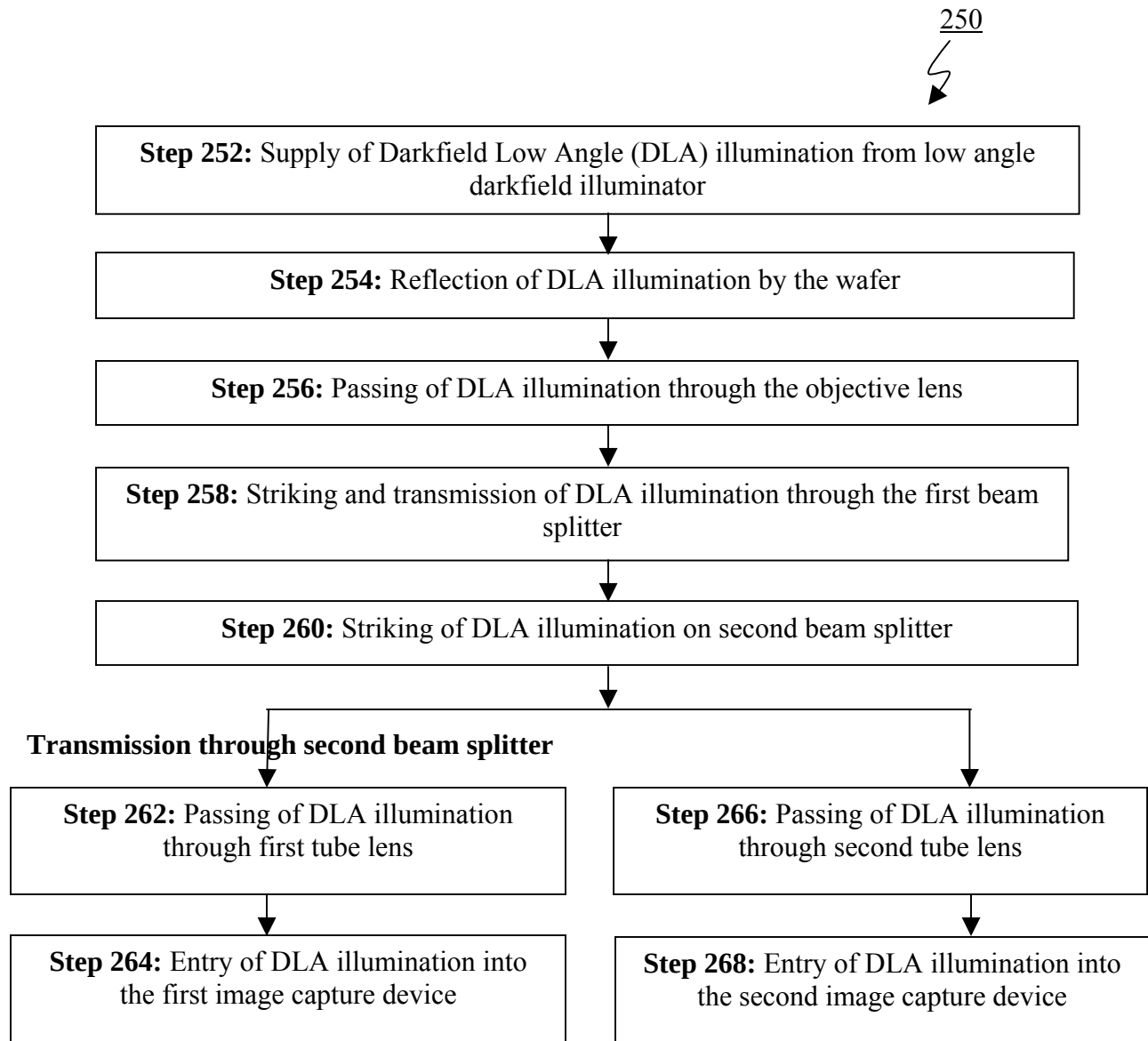


FIG. 12

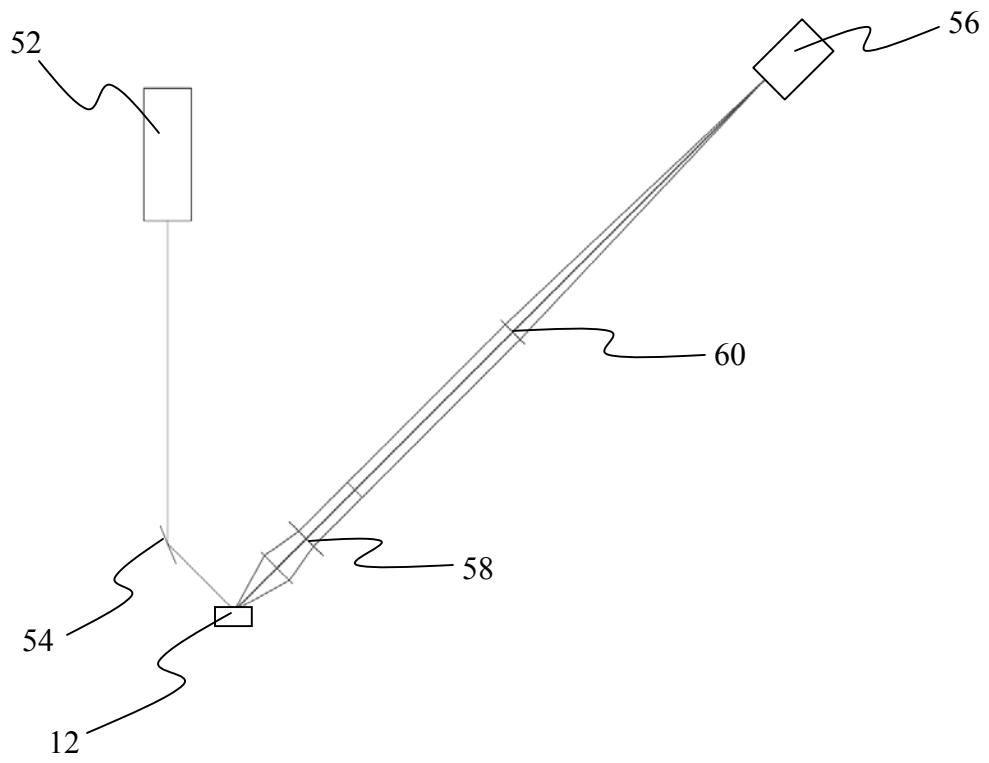
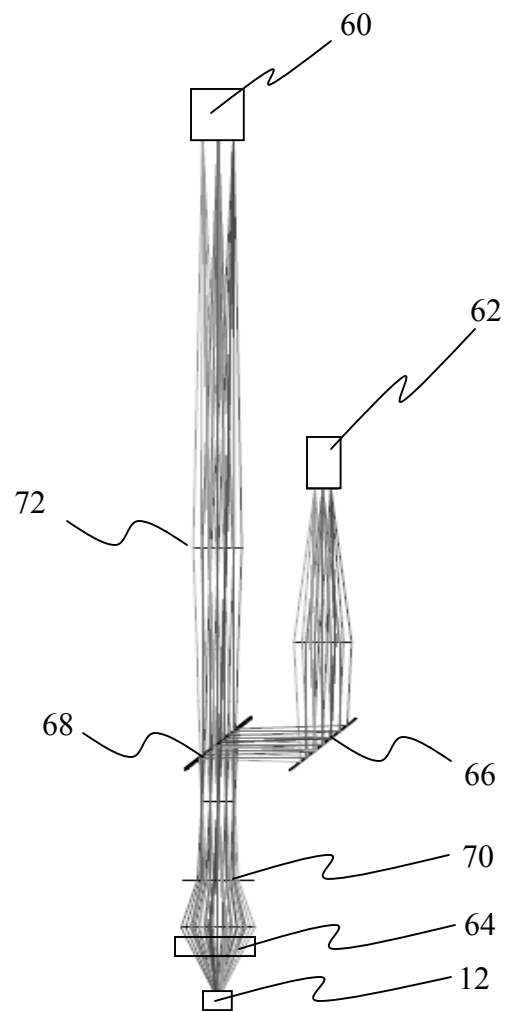


FIG. 13

**FIG. 14**

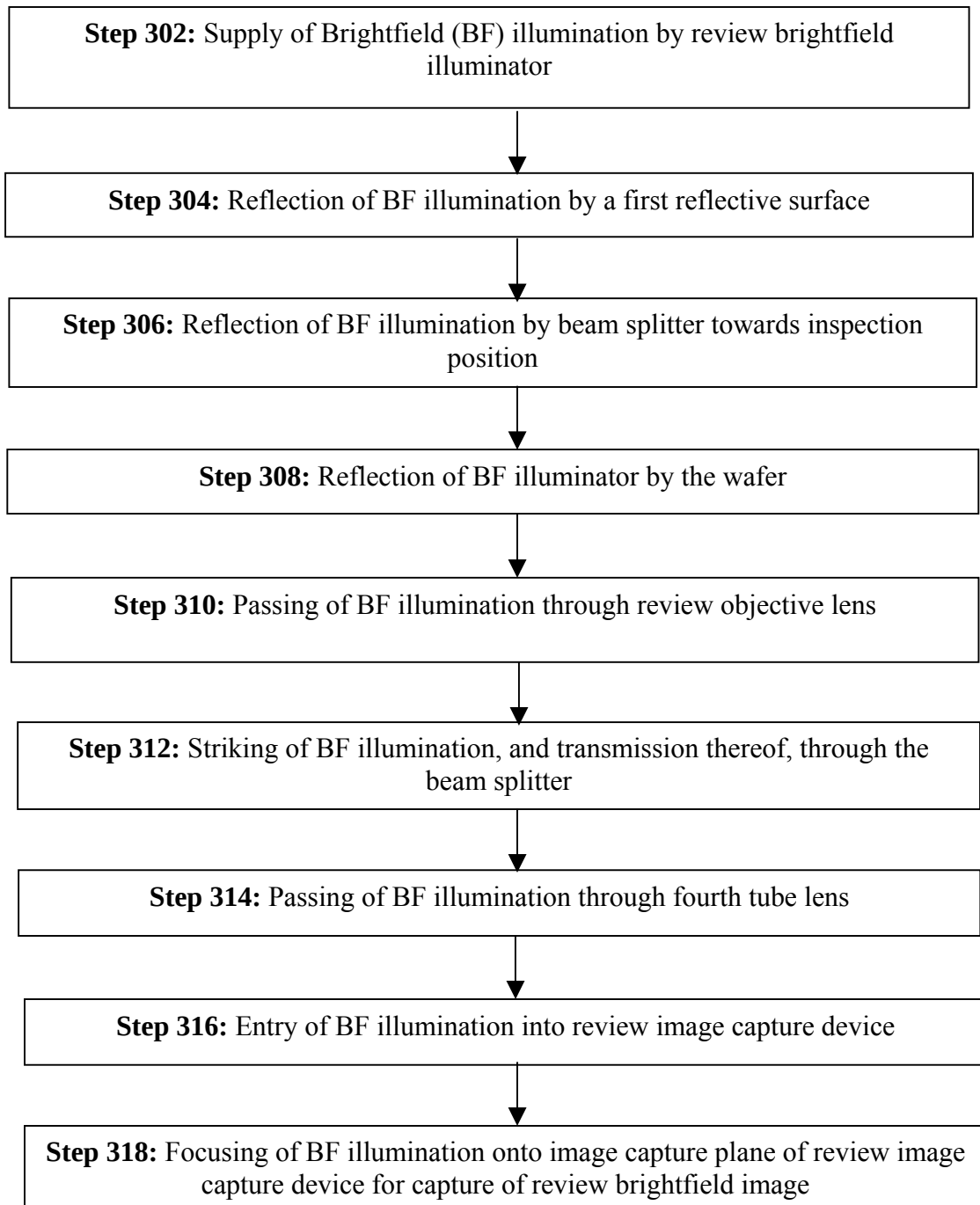
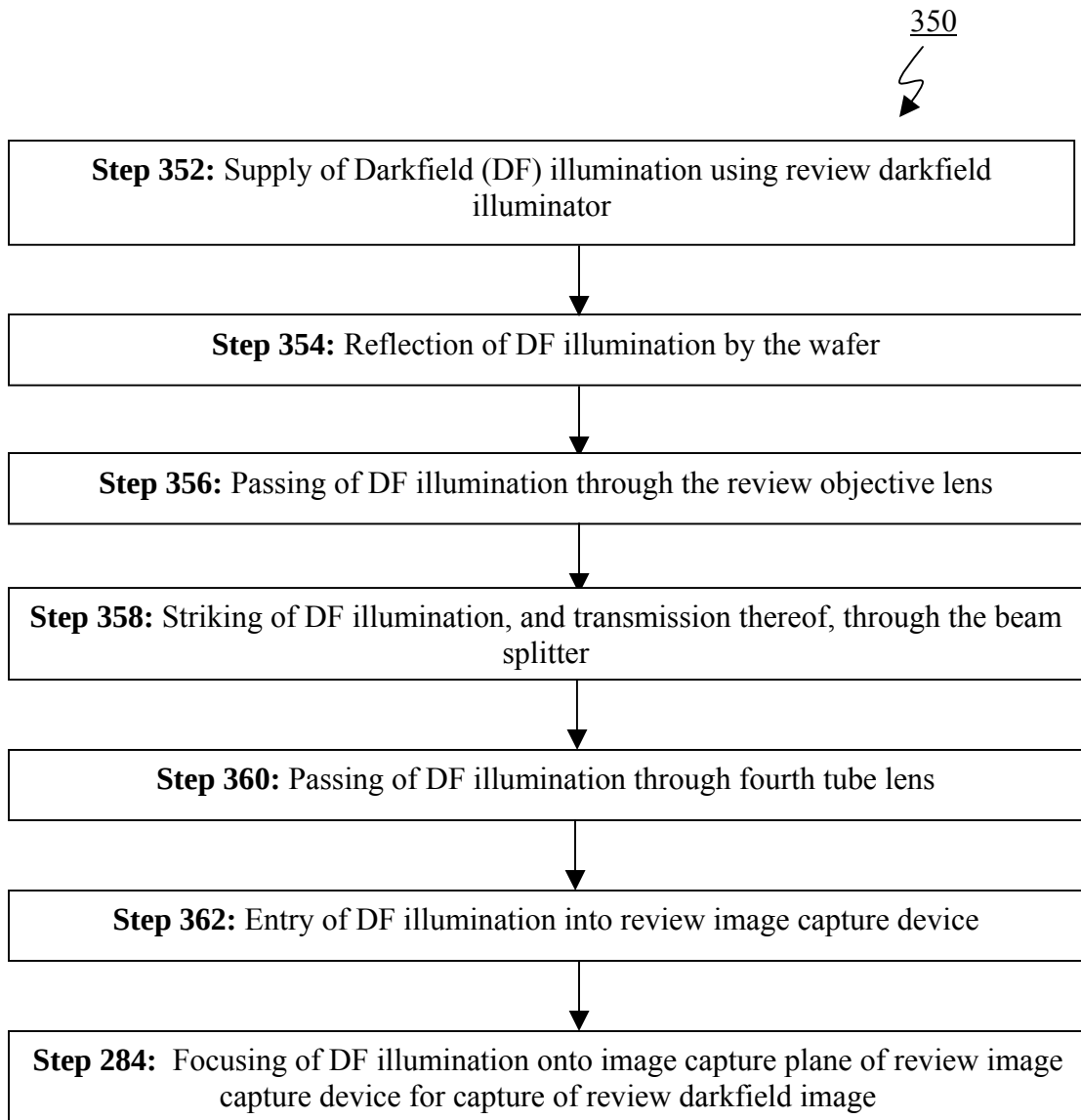


FIG. 15

**FIG. 16**

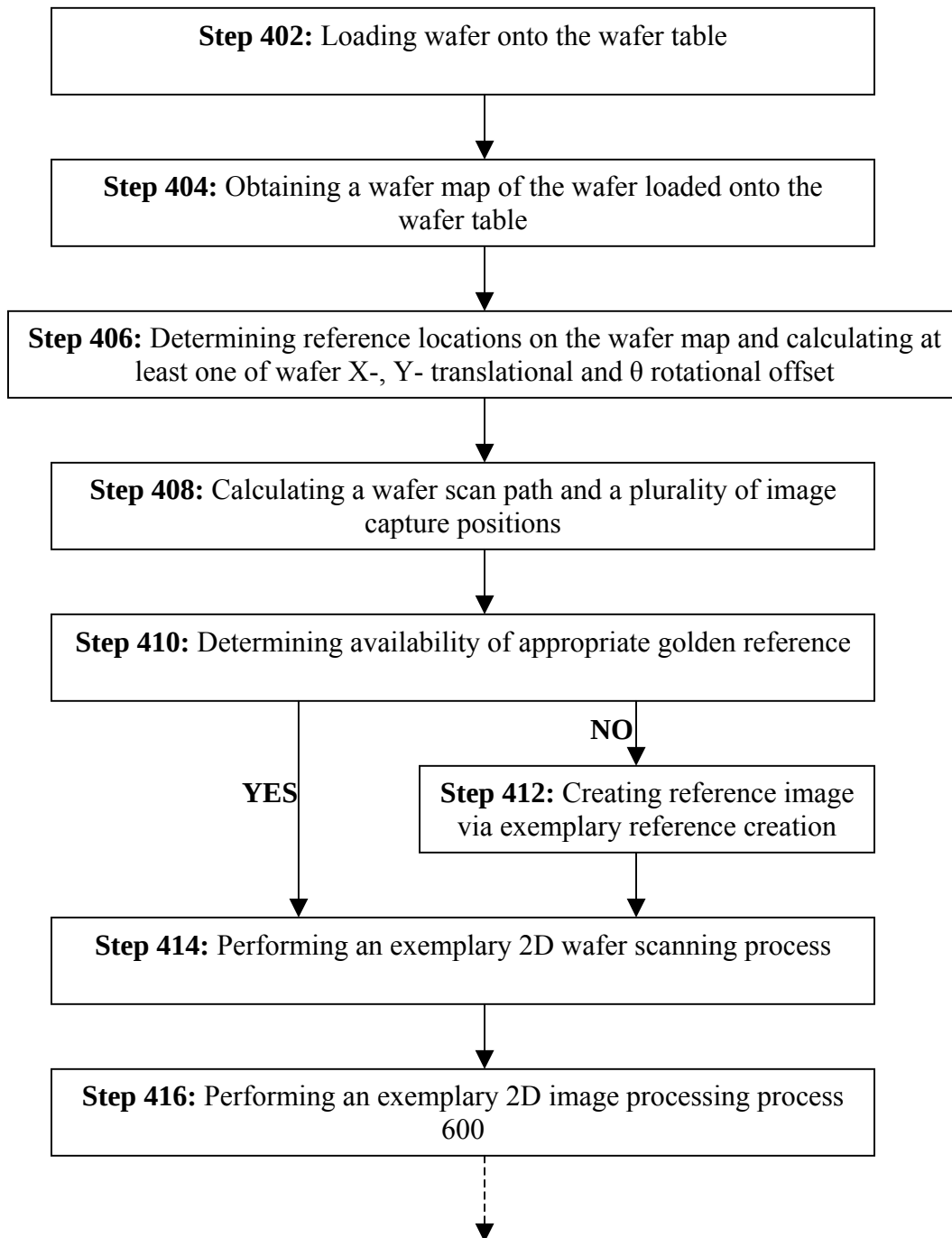
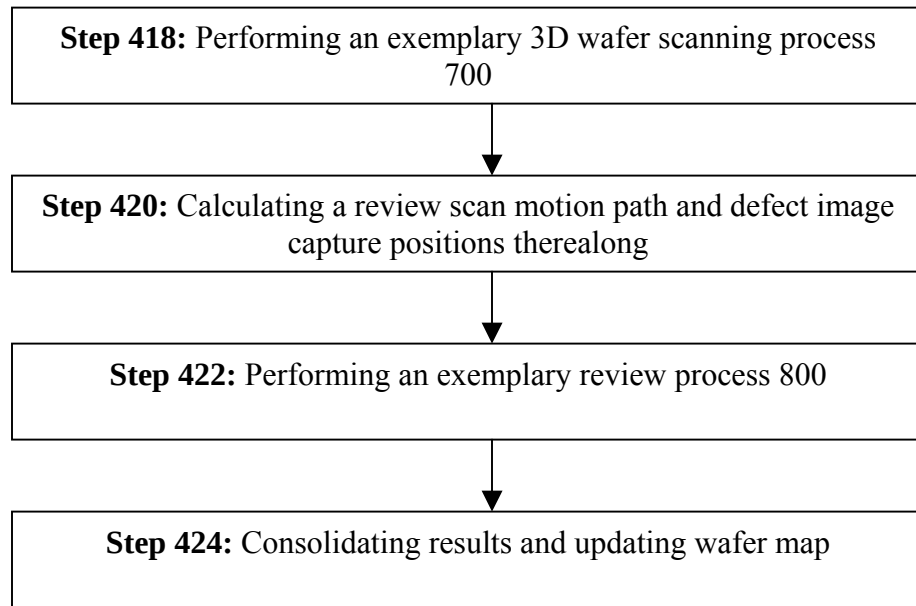


FIG. 17

**FIG. 17**

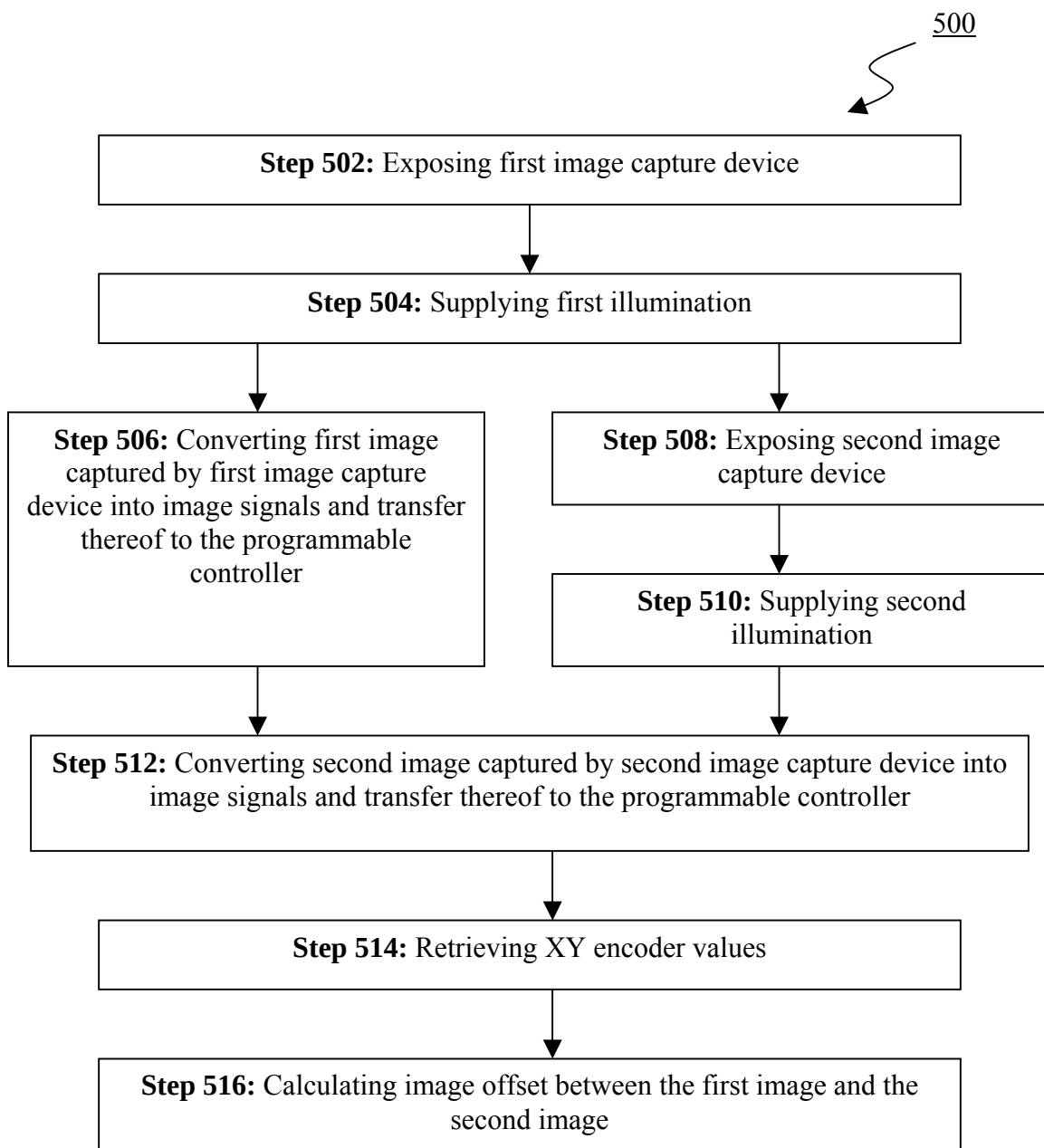
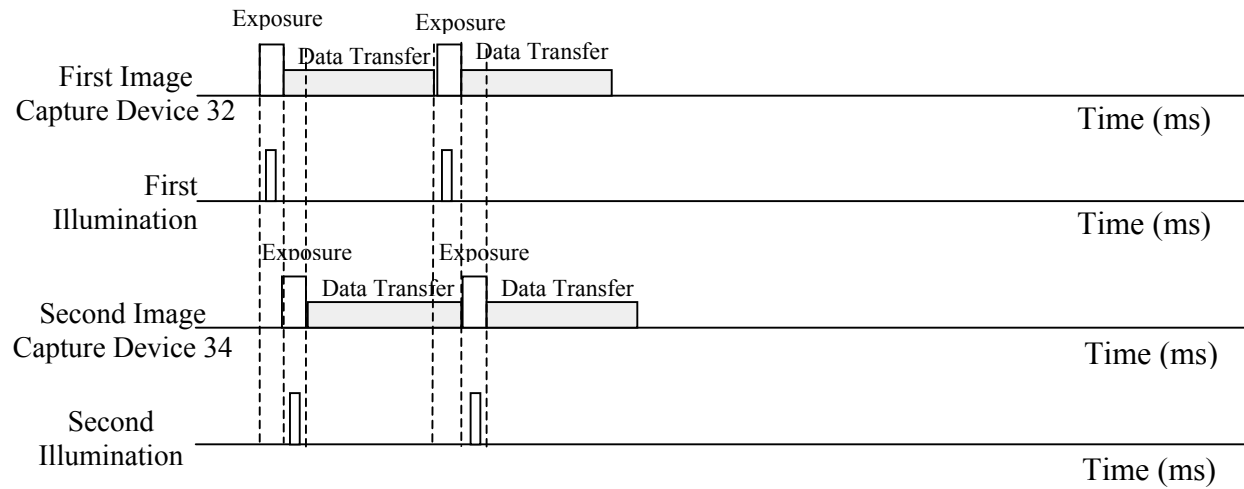


FIG. 19

Table of Illumination Configurations Selectable by Illumination Configurator

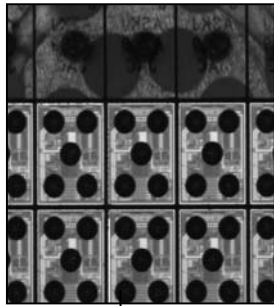
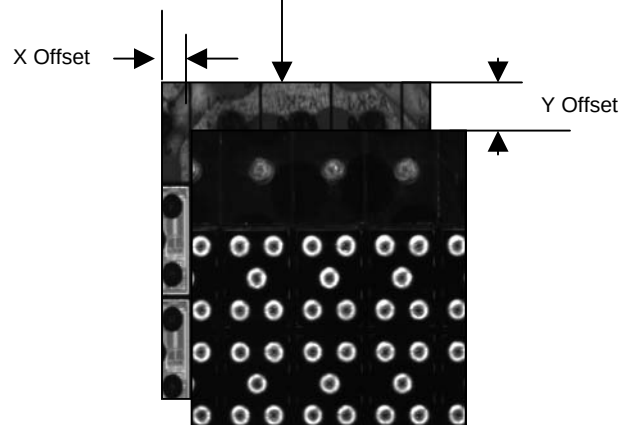
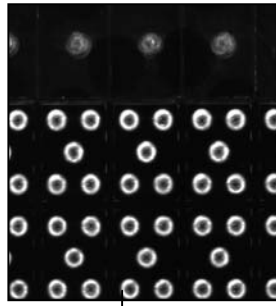
Configuration	First Illumination Supplied	Second Illumination Supplied
1	Brightfield	High Angle Darkfield
2	Brightfield	Low Angle Darkfield
3	Brightfield + High Angle Darkfield	High Angle Darkfield
4	Brightfield + High Angle Darkfield	Low Angle Darkfield
5	Brightfield	High Angle Darkfield + Low Angle Darkfield
6 (with same illumination but varying intensity level)	Brightfield with intensity level (e.g. 50%)	Brightfield with intensity level (e.g. 25%)
7	High Angle Darkfield	Brightfield
8	Brightfield + High Angle Darkfield	Brightfield + Low Angle Darkfield
9	High Angle Darkfield with intensity level (e.g. 60%)	High Angle Darkfield with intensity level (e.g. 50%)

FIG. 20



Timing chart of 2D image acquisition from first and second image capture devices

FIG. 21

FIG. 22a First Image**FIG. 22b Second Image****FIG. 22c Combined first Image and second image demonstrating image offset due to image capture while wafer is moving**

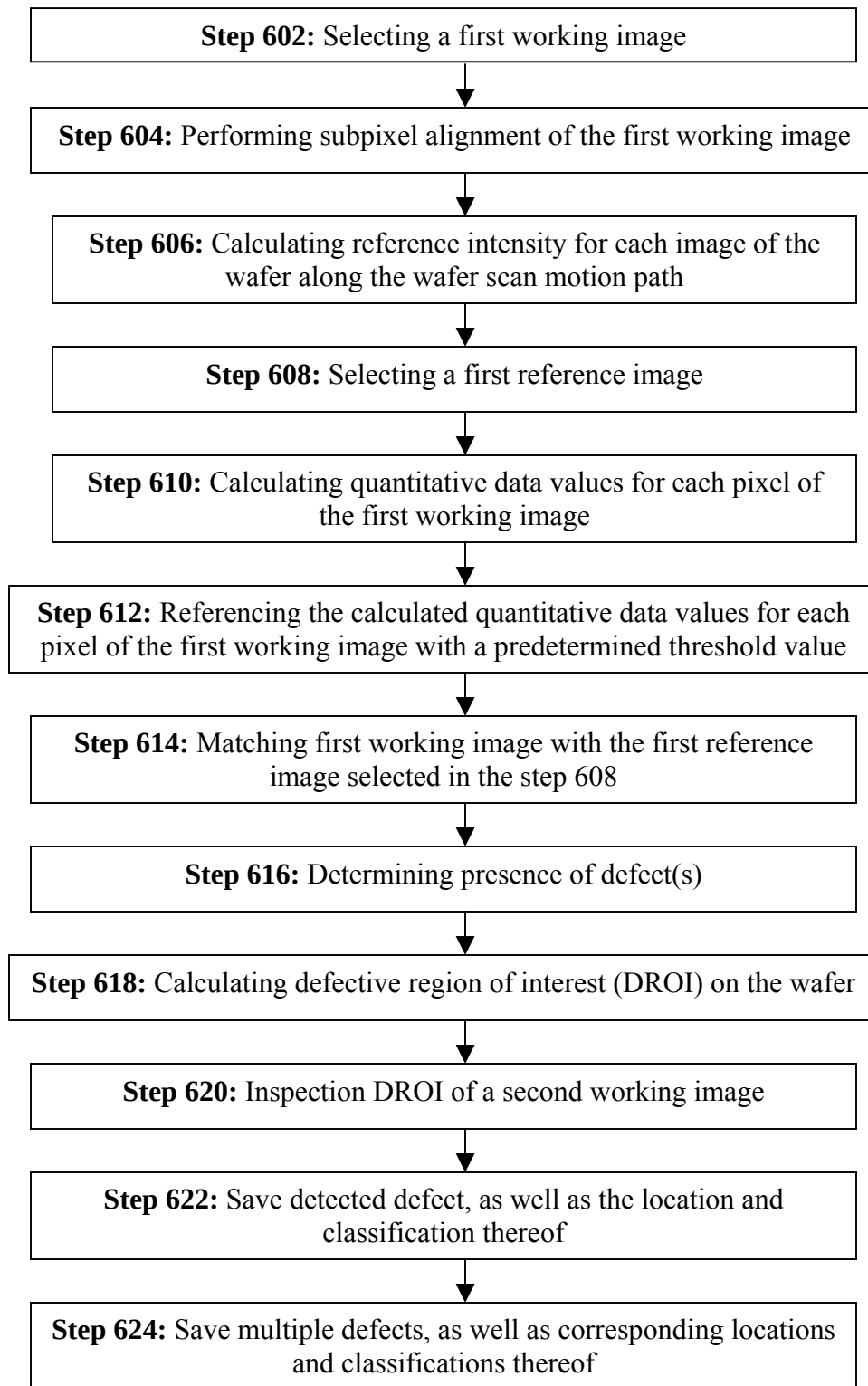


FIG. 23

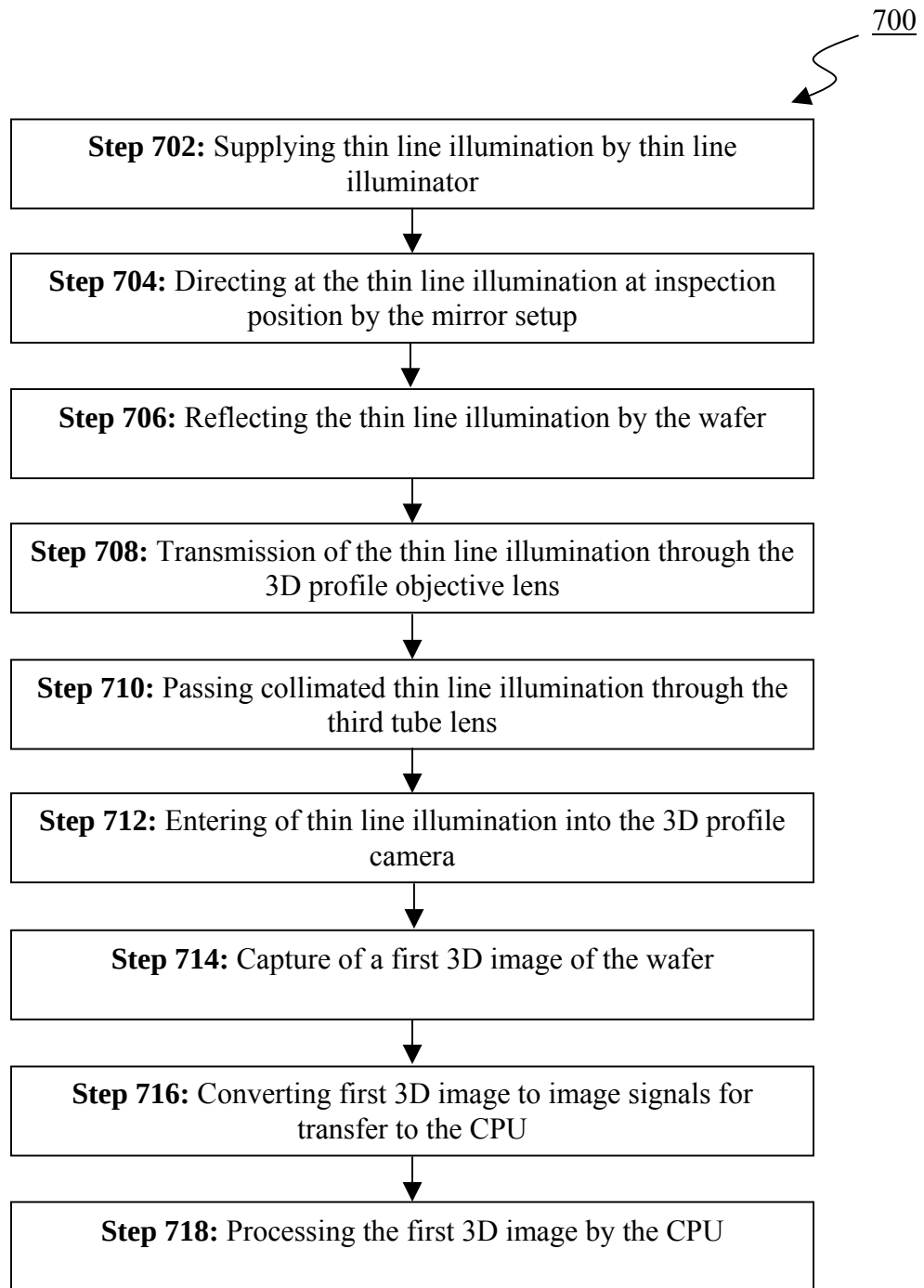


FIG. 24

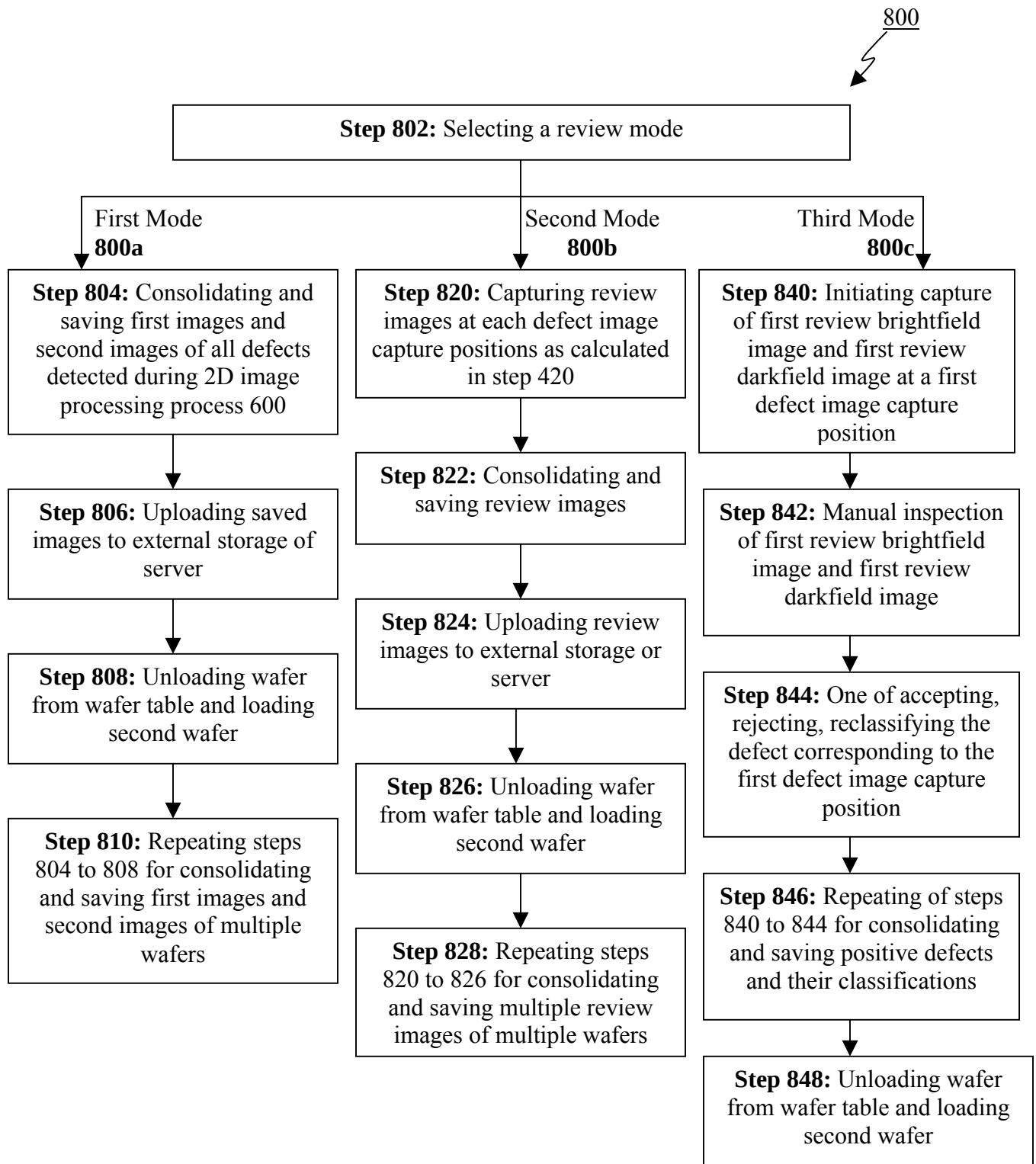


FIG. 27

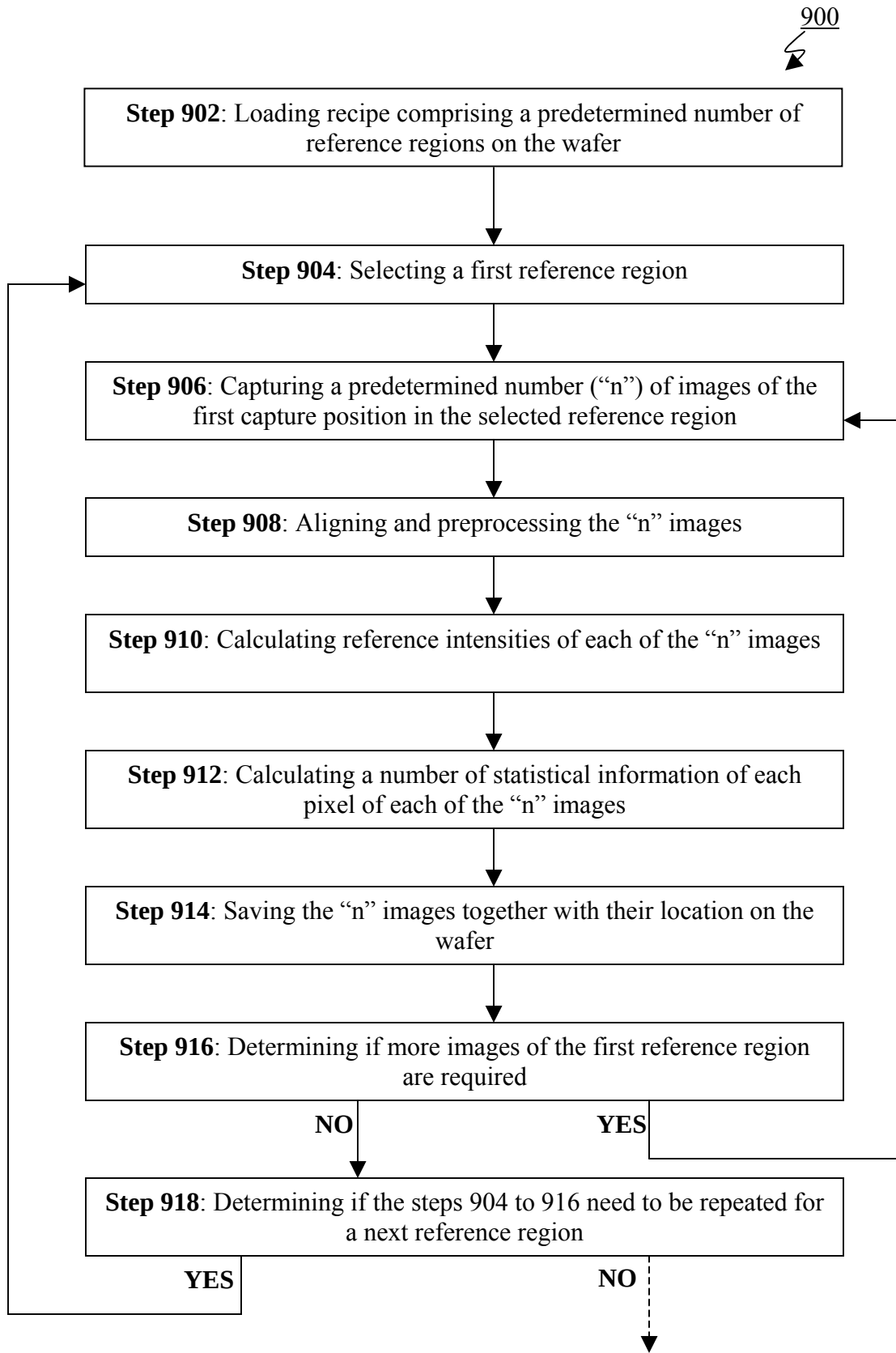
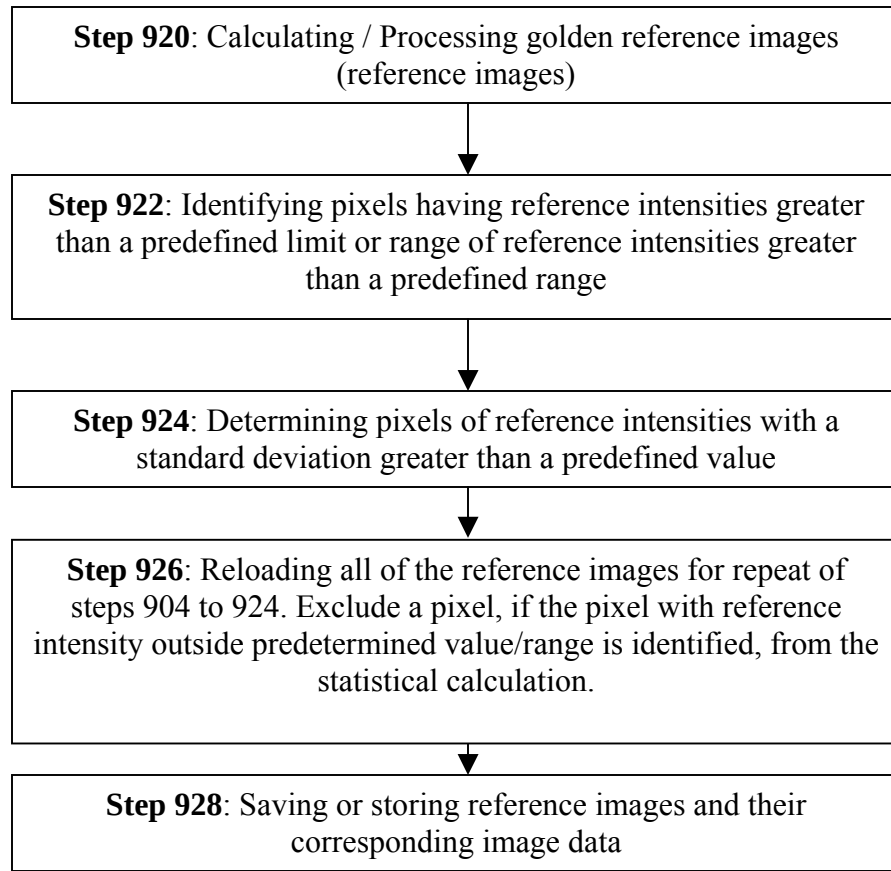


FIG. 18

**FIG. 18**

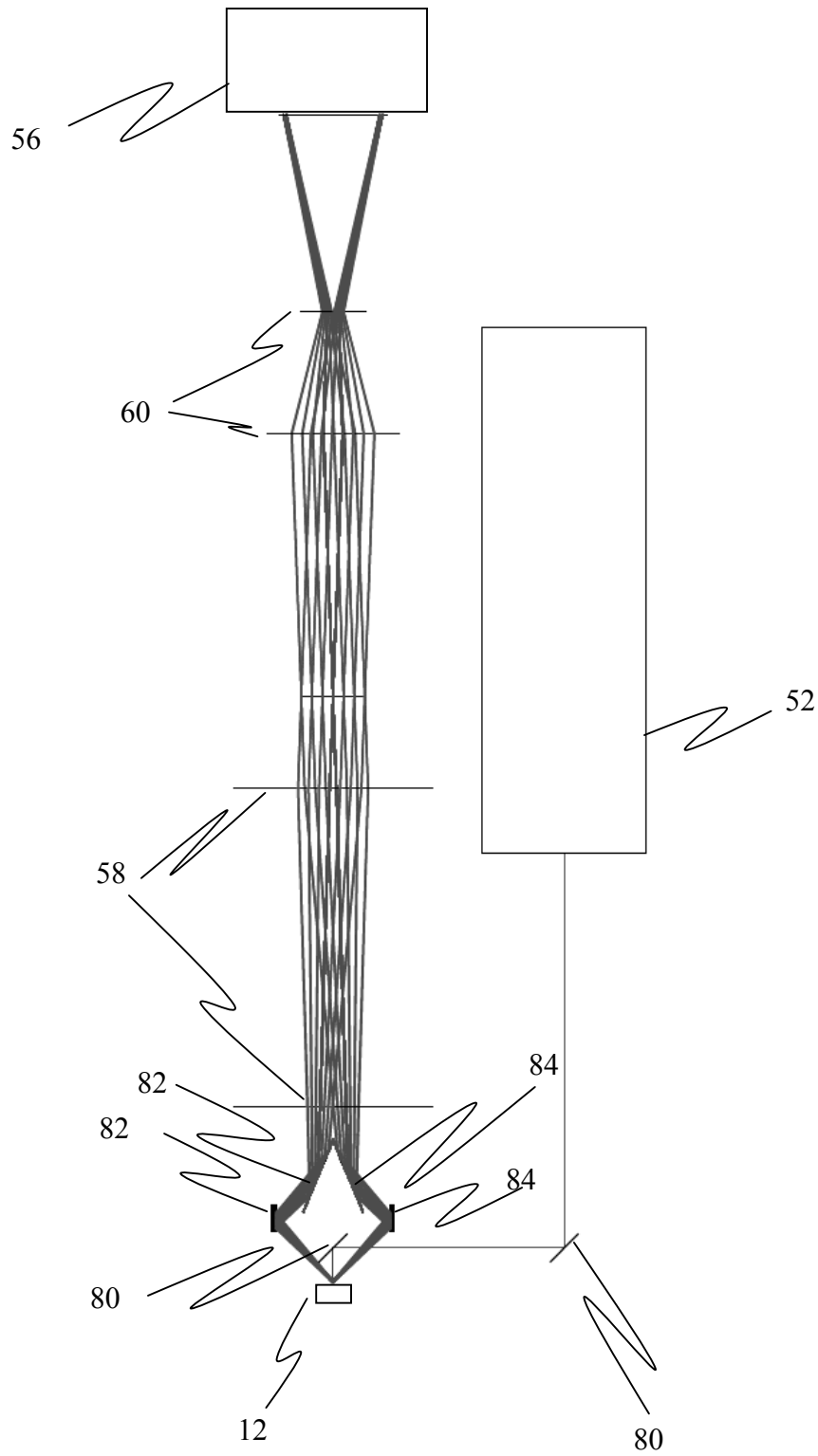


FIG. 25

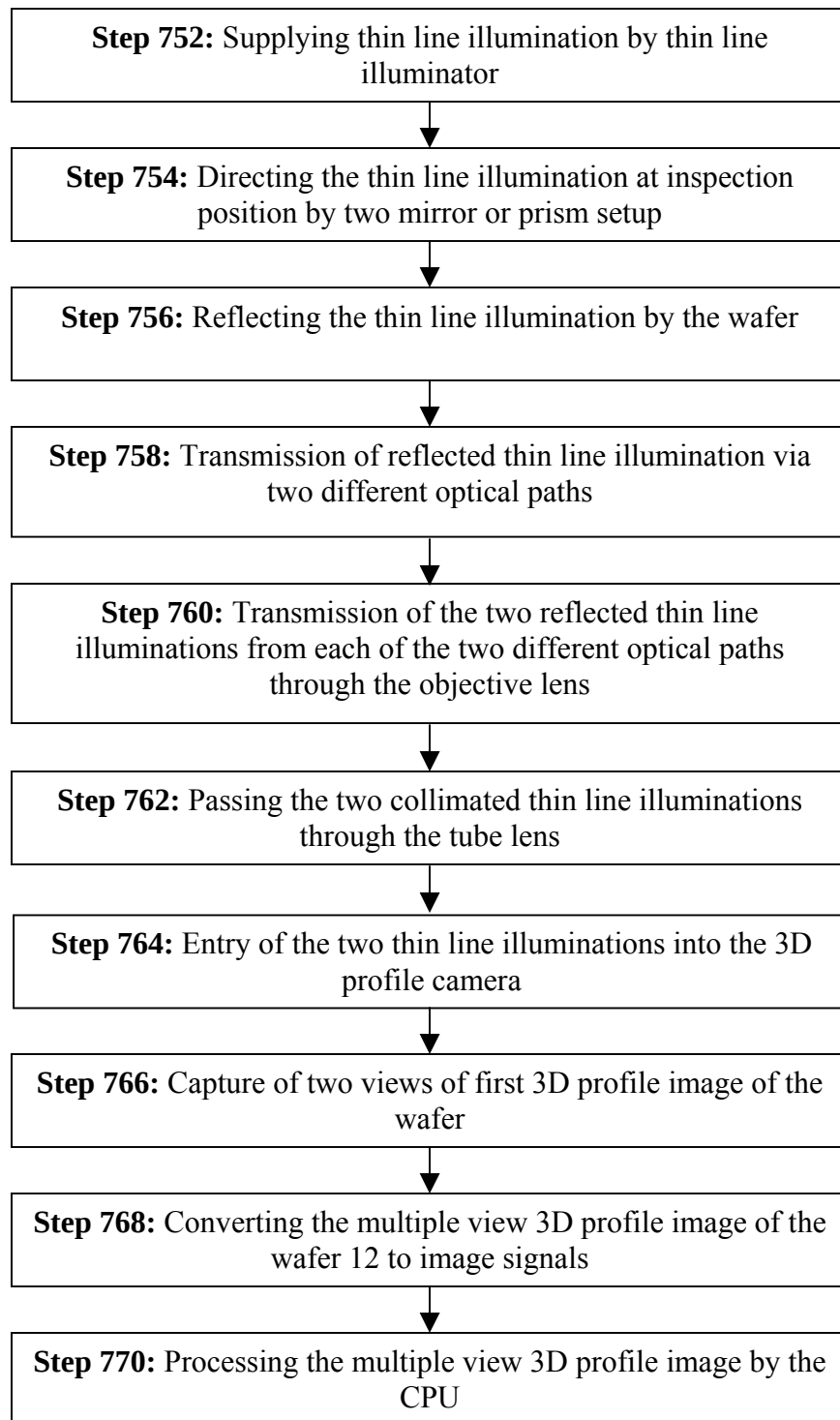


FIG. 26